

Soldering Profile

All of the components must be dried prior to assembly as follows:

1. Samples and package type B1 and B5, bulk components - the recommended drying process is to be done at 125°C for 48 hours.
 2. For package type T1 and T2 - per JEDEC J-STD-033 level 5.
- For taped components the recommended drying process is to be done at maximum 70°C.

